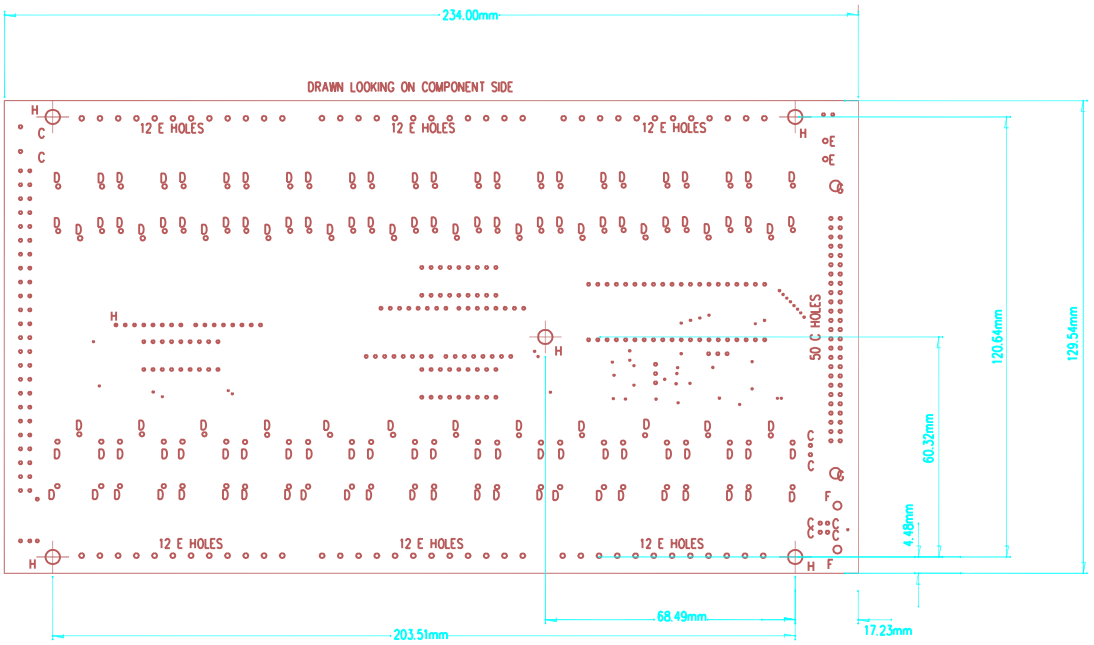

MATERIAL:
EPOXIDE RESIN BONDED GLASS FABRIC
FR4 TO BS4584 PT.4
2 LAYER 2oz COPPER 1.6mm THICK

FINISH
HOT AIR LEVEL FINISH
SOLDER RESIST PROBIMER 52 (GREEN) BOTH SIDES
SILKSCREEN COMPT SIDE - WHITE NOTATION INK

ALL HOLES TO BE PLATED THROUGH UNLESS OTHERWISE STATED
HOLES IDENTIFIED THUS:* ARE NON PTH
ALL HOLE SIZES APPLY AFTER PLATING THROUGH
PROFILE BOARD TO DIMENSIONS GIVEN, EDGES TO BE FREE OF
COPPER AFTER PLATING

DRILL DATA

A HOLES	0.5mm(0.050") DIA	47 OFF (UNREF VIAS)
B HOLES	0.9mm(0.036") DIA	202 OFF (UNREF COMP)
C HOLES	1.0mm(0.040") DIA	58 OFF
D HOLES	1.3mm(0.052") DIA	120 OFF
E HOLES	1.4mm(0.056") DIA	74 OFF
F HOLES	2.3mm(0.090") DIA	2 OFF
G HOLES	3.0mm(0.120") DIA	2 OFF
H HOLES	4.0mm(0.157") DIA	5 OFF

MANUFACTURING FILES

100_DA_2006_003P-B-L1.SPL LAYER1 (COMPONENT SIDE)
100_DA_2006_003P-B-L2.SPL LAYER2 (SOLDER SIDE)
100_DA_2006_003P-B-SSL1.SPL SILKSCREEN (COMPT SIDE)
100_DA_2006_003P-B-SRL1.SPL SOLDERMASK (COMPT SIDE)
100_DA_2006_003P-B-SRL2.SPL SOLDERMASK (SOLDER SIDE)
100_DA_2006_003P-B-NCD.SPL NC DRILL FILE
100_DA_2006_003P-B-NCD.REP DRILL SIZE REP
100_DA_2006_003P-B-DWG.SPL DRILL DWG (THIS DWG)

100_DA_2006_003P-B-SPL1.SPL SOLDERPASTE (COMPT SIDE)

ISSUE	ECO	DATE
B		APR 07
A		FEB 07

GOLDCHIP COMPUTERS Ltd.
BROOK LANE, CORFE MULLEN,
WIMBORNE, DORSET. BH21 3RD

TITLE DRILL & PROFILE DETAILS
DO24Mx(USB) POWER RELAY CARD

This drawing is supplied on the understanding that the information it contains will not be copied, disclosed to others or used for any purpose other than for which it is supplied, except with written consent.

TOLERANCES
GENERAL +/-0.3
HOLE DIA +0.1 -0
AFTER PLATING +0.1 -0
UNLESS STATED OTHERWISE

DRAWN	CHECKED	APPROVED	USED ON
GPD 3206P			A3
FEB 07			
CAD GENERATED DRAWING			SHT OF SHTS
DRG. NO. 100/DA/2006/003P			